

GSGP011BSL

Surface Mount Schottky Rectifier Reverse Voltage 100V Forward Current 1A

Features

- · Low forward voltage drop
- · Low leakage current
- Moisture sensitivity: level 1, per J-STD-020
- Solder dip 260 °C, 10 s
- · Low profile, typical thickness 1.0mm



Package: eSGP (SOD-323F)



Applications

For use in fast swiching in RF module, lighting, cell phone, portable devices, power supplie and other consumer applications.

Maximum Ratings ($T_A = 25$ °C unless otherwise noted)

Parameter	Symbol	Value	Unit
Maximum Repetitive Peak Reverse Voltage	V_{RRM}	100	V
Maximum RMS Voltage	V_{RMS}	70	V
Maximum DC Blocking Voltage	V_{DC}	100	V
Maximum Average Forward Rectified Current	I _{F(AV)}	1.0	Α
Peak Forward Surge Current (8.3 ms single half sine-wave superimposed on rated load)	I _{FSM}	30	А
Operation Junction Temperature Range	TJ	- 55 to + 150	°C
Storage Temperature Range	T_{STG}	- 55 to + 150	°C

Electrical Characteristics (T_A = 25°C unless otherwise noted)

Parameter	Test Conditions	Symbol	Value	Unit
Maximum Instantaneous Forward Voltage	I _F =1A	V _F	0.80	V
Maximum DC Reverse Current at Rated DC Blocking Voltage	T _A =25°C	I _R	20	μA
Typical Junction Capacitance	4.0 V, 1 MHz	C _J	24	pF
Typical Thermal Resistance ¹⁾	Juntion to Mount	$R_{\theta JM}$	60	°C/W

Note:1) The thermal resistance from junction to ambient, case or mount, mounted on P.C.B with 5×5mm copper pads, 2 OZ, FR4 PCB

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Ratings and Characteristics Curves (T_A = 25°C unlessotherwise noted)

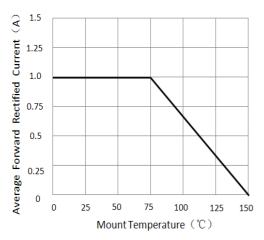


Figure 1. Forward Current Derating Curve

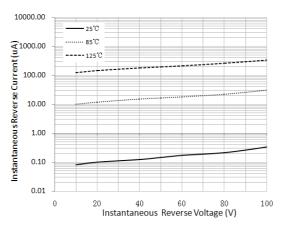


Figure 3. Typical Reverse Characteristics

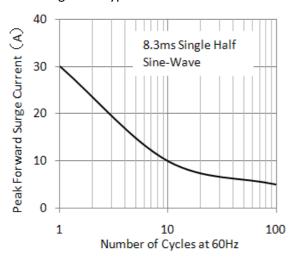


Figure 5. Maximum Non-Repetitive Peak **Forward Surge Current**

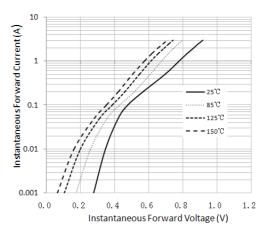


Figure 2. Typical Instantaneous Forward Characteristics

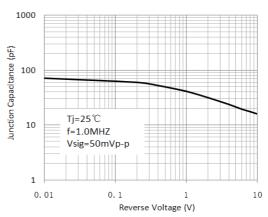


Figure 4. Typical Junction Capacitance

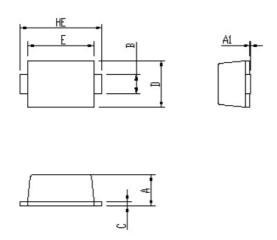


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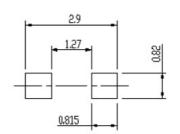
Package Outline Dimensions

eSGP (SOD-323F)



DIM	Unit	: mm	Unit: inch		
	MIN	MAX	MIN	MAX	
Α	0.9	1.08	0.035	0.043	
A1	0	0.1	0.000	0.004	
В	0.5	0.7	0.020	0.028	
С	0.1	0.25	0.004	0.010	
D	1.4	1.6	0.055	0.063	
Е	2	2.2	0.079	0.087	
L	0.35	0.65	0.014	0.026	
HE	2.4	2.8	0.094	0.110	

Soldering footprint



Packing Information Packing quantities

- 1) 3000 pcs/Reel, 40 Reels/Box, 8mm Tape, 7" Reel
- 2) 10000 pcs/Reel, 16 Reels/Box, 8mm Tape, 13" Reel

